

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

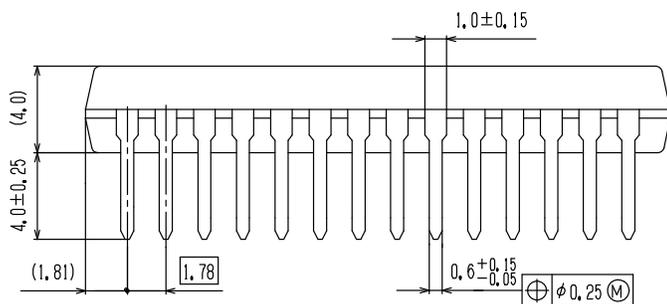
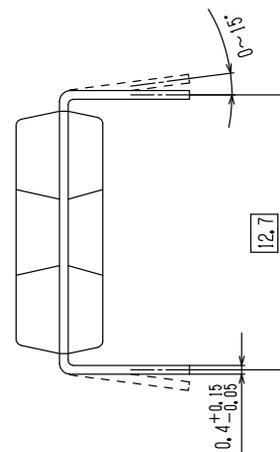
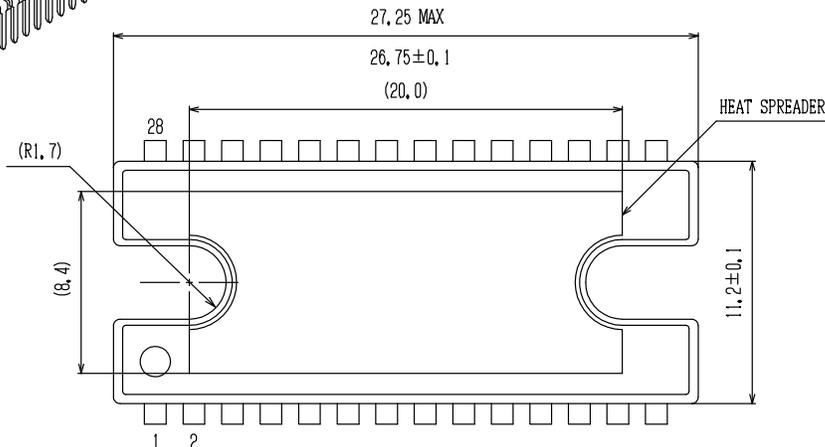
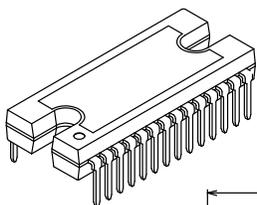
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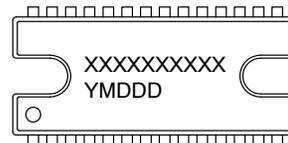
### PDIP28 W/ HEAT SPREADER / DIP28H (500 mil)

CASE 646AX  
ISSUE A

DATE 16 OCT 2013



#### GENERIC MARKING DIAGRAM\*



XXXXX = Specific Device Code  
Y = Year  
M = Month  
DDD = Additional Traceability Data

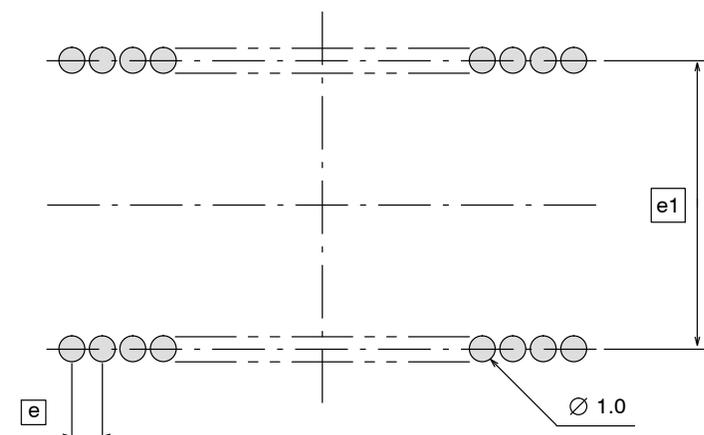
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

(Unit: mm)

Reference symbol	Package name
	DIP28H (500 mil)
e1	12.70
e	1.78

○ Through Hole Area

#### SOLDERING FOOTPRINT\*



NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>PDIP28 26.75X11.2MM, 1.78P W/ HEAT SPREADER / DIP28H (500MIL)</b>	<b>PAGE 1 OF 1</b>

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